

DIN-Power F048MR-3,0C1-2-clip

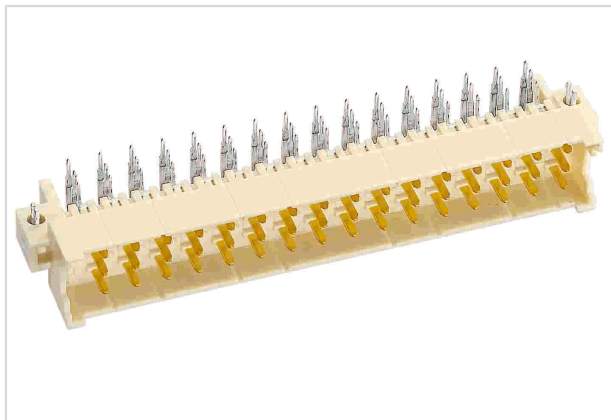


Image is for illustration purposes only. Please refer to product description.

Part number	09 06 348 6951
Specification	DIN-Power F048MR-3,0C1-2-clip
HARTING eCatalogue	https://b2b.harting.com/09063486951

Identification

Category	Connectors
Series	DIN 41612
Identification	Type F
Element	Male connector
Description of the contact	Angled
Features	Colour deviations and speckles permitted

Version

Termination method	Reflow soldering termination (THR)
Connection type	Motherboard to daughtercard
	Extender card
	PCB to cable
Number of contacts	48
Contact configuration	Rows z, d and b, positions 2, 4, ... , 30, 32
Coding	Hole coding
	Shroud coding
	Coding with loss of contacts
	D20 coding
PCB fixing	With fixing flange
	With snap-in clip

Technical characteristics

Contact rows	3
Contact spacing (termination side)	2.54 mm
	5.08 mm



Pushing Performance

Technical characteristics

Contact spacing (mating side)	3.81 mm 5.08 mm
Rated current	6 A
Rated current	Rated current measured at 20 °C, see derating curve for details
Clearance distance	≥1.6 mm
Creepage distance	≥3 mm
Insulation resistance	>10 ¹² Ω
Contact resistance	≤15 mΩ
Limiting temperature	-55 ... +125 °C (during reflow soldering max. +240 °C for 15 s)
Insertion and withdrawal force	≤75 N
Performance level	2 acc. to IEC 60603-2
Mating cycles	≥400
Test voltage U _{r.m.s.}	1.55 kV (contact-contact) 2.5 kV (contact-ground)
Isolation group	II (400 ≤ CTI < 600)
PCB thickness	1.6 mm ±0.2
Hot plugging	No

Material properties

Material (insert)	Thermoplastic resin, glass-fibre filled
Colour (insert)	Beige
Material (contacts)	Copper alloy
Surface (contacts)	Noble metal Mating side Sn over Ni Termination side
Material flammability class acc. to UL 94	V-0
RoHS	compliant
ELV status	compliant
China RoHS	e
REACH Annex XVII substances	No
REACH ANNEX XIV substances	No
REACH SVHC substances	No

Specifications and approvals

Specifications	IEC 60603-2
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Pushing Performance

Specifications and approvals

UL / CSA

UL 1977 ECBT2.E102079
 CSA-C22.2 No. 182.3 ECBT8.E102079

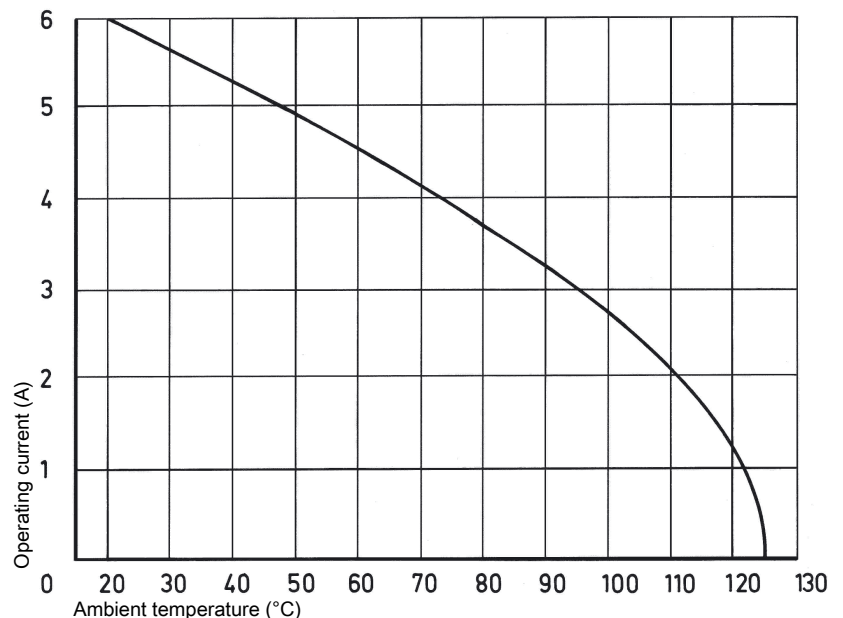
Railway classification F4/I3 acc. to NFF 16-101/102

Commercial data

Packaging size	20
Net weight	22.96 g
Country of origin	Germany
European customs tariff number	85366990
eCl@ss	27460201 PCB connector (board connector)

Current carrying capacity

The current carrying capacity of the connectors is limited by the thermal load capability of the contact element material including the connections and the insulating parts. The derating curve is therefore valid for currents which flow constantly (non-intermittent) through each contact element of the connector evenly, without exceeding the allowed maximum temperature.
 Measuring and testing techniques acc. to IEC 60512-5-2



Quantity of solder paste

Before the components are assembled, solder paste must be applied to all the solder pads (for connecting surface-mount components) and the plated through holes. To ensure that the plated through holes are completely filled, significantly more solder paste must be applied than traditional solder pads on the pcb surface. There are numerous calculation methods available which are complicated to apply. The following rule of thumb has proved valuable in practice.

Required volume of paste = 2 (Volume of plated through hole - Volume of the connector termination in the hole)

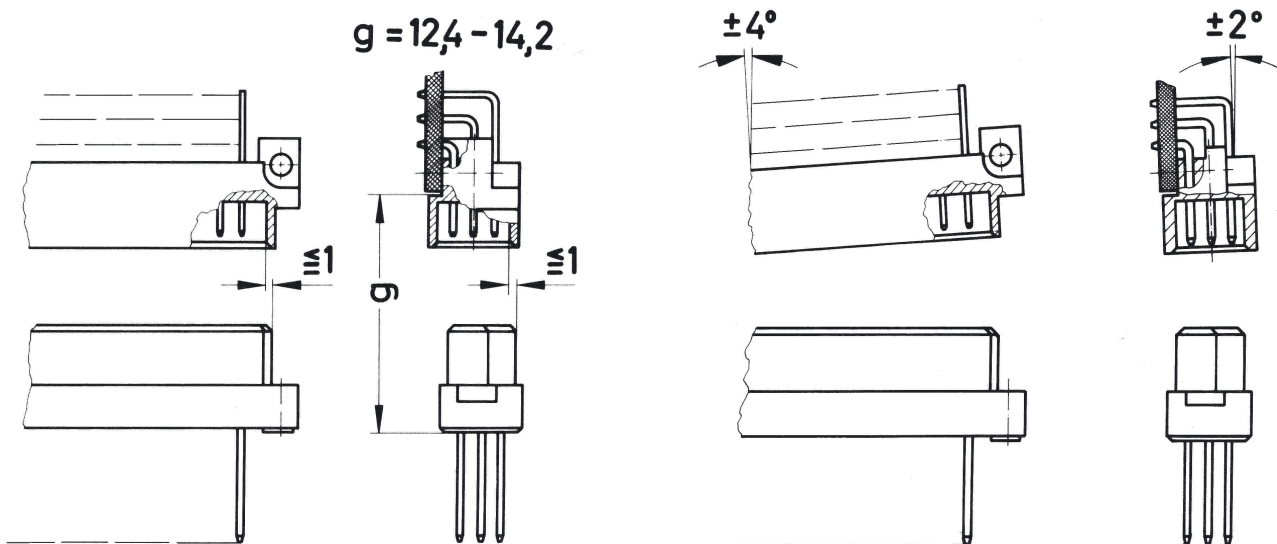
Comment: the multiplier "2" compensates for solder paste shrinkage during soldering. For this purpose, it was assumed that 50% of the paste consists of the actual solder, the other 50% being soldering aids.

Soldering instructions

THR (ThroughHoleReflow) connectors are designed to be used in a reflow oven together with other SMD (SurfaceMountDevice) components. In the process, called as well "Pin in Hole Intrusive Reflow", the connectors are inserted into plated through holes in a comparable way to conventional component mounting. All other components can be assembled on the pcb surface.

The length of the connector contacts should be such that they protrude by no more than 1.5 millimetres after insertion to the pcb. Each contact collects solder on its tip as it penetrates the solder paster in the hole. So if the contact is too long, this solder would no longer be able to reflow back into the plated through hole by capillary action during the soldering process, therefore the quality of the soldered connection would suffer as a result.

Mating conditions



To ensure reliable connections and prevent unnecessary damage, please refer to the application data diagrams. These recommendations are set out in IEC 60603-2.

The connectors should not be coupled and decoupled under electrical load.